

Appln No. 10/760255
Amdt. Dated: November 09, 2006
Response to Office Action of September 19, 2006

3

REMARKS/ARGUMENTS

In response to the detailed Office Action dated September 19, 2006, the Applicant offers the following submissions.

Specification

The Applicant has updated pages 1 and 2 of the specification by replacing the paragraph entitled "Cross-Reference to Co-Pending Applications". The Applicant has replaced the US application numbers with corresponding granted US patent numbers, where application. The Applicant submits that these amendments introduce no new matter.

35 U.S.C. §102 - Claims 1 to 5

Claims 1 to 5 stand rejected for lack of novelty in light of US 6,439,908 to Silverbrook. The Applicant submits that '908 does not support a §102 rejection of claim 1 and therefore dependent claims 2 to 5.

The '908 reference does not disclose several fundamental elements defined in claim 1. Firstly, there is no disclosure of a controller connected to one or more of the printhead integrated circuits for controlling the operation thereof. It is well understood in this field that a controller for the printhead ICs needs to have the capacity for data processing. In '908, the flexible printed circuit board 54 and the individual TAB films 22 have no micro processing ability; they are simply the electrical connection between the busbars 58, 60, the sixty-two pin connector 66 and the printhead ICs 18. They have no control over the operation of the printhead ICs. The lack of any drive electronics in '908 was raised in our response to the first Office Action but we note the Examiner has not responded to this point.

Secondly, the citation does not teach a module that is removably mounted to a casing. The Examiner equates the printhead assembly 10 to the printhead module of claim 1. The chassis 14 is equated to the casing (despite being a part of the assembly 10). Leaving aside the fact that the assembly 10 (module) and the chassis 14 (casing) are not separate integers (the chassis is one component of the assembly), it is clear that the reservoir molding 32 and the lid molding 76 are permanently secured to the chassis 14 by heat stakes 88 and 90 which are thermo-plastically deformed at assembly. The parts are not configured to disassemble and subsequently reassemble.

Thirdly, the '908 printhead ICs 18 are not fixedly mounted to the support member. The Examiner argues that the '908 support member is the reservoir molding 32 and the individual cover moldings 28. The cover moldings 28 are the bodies of the replaceable printhead modules 12 that releasably engage the reservoir molding 32 (see col. 5, lines 39-42). Hence, the printhead ICs are fixedly mounted to the cover moldings 28 only. They are removable from the reservoir molding 32. Clearly, the '908 printhead ICs 18 are not fixedly mounted to a support member that carries printing fluid to all the printhead ICs.

Appln No. 10/760255
Amdt. Dated: November 09, 2006
Response to Office Action of September 19, 2006

4

In light of the above, the '908 reference does not teach all the essential elements of claim 1 and therefore fails to anticipate any of claims 1 to 5.

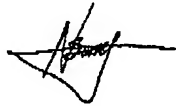
It is respectfully submitted that all of the Examiner's objections have been successfully traversed. Accordingly, it is submitted that the application is now in condition for allowance. Reconsideration and allowance of the application is courteously solicited.

Very respectfully,

Applicants:



Kia Silverbrook



Norman Micheal Berry



Garry Raymond Jackson



Akira Nakazawa

C/o: Silverbrook Research Pty Ltd
393 Darling Street
Balmain NSW 2041, Australia
Email: kia.silverbrook@silverbrookresearch.com
Telephone: +612 9818 6633
Facsimile: +61 2 9555 7762